

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				ATTY DOCKET NO. FIS920040098US1		APPLICATION NO. 10/711,076		
				Bernier et al.				
				FILING 8/20/04		GROUP ART Unknown		
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
U.S. PATENT APPLICATION PUBLICATIONS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
OF		2001127108	11/05/01	Japan				
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)								
EXAMINER				DATE CONSIDERED				
				6/15/06				

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	COMPRESSIBLE FILMS SURROUNDING SOLDER CONNECTORS
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Application Number :

Confirmation Number:

First Named Applicant: William Bernier

Attorney Docket Number: FIS920040098US1

Art Unit:

Examiner:

Search string: (6483191 or 5274913 or 6281452 or 6573122 or 6100114 or 20030230792).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents


init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
DF	1	6483191	2002-11-19	Umezaki			
DF	2	5274913	1994-01-04	Grebe et al			
DF	3	6281452	2001-08-28	Prasad et al			
DF	4	6573122	2003-06-03	Standing			
DF	5	6100114	2000-08-08	Milkovich et al			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
DF	1	20030230792	2003-12-18	Wu et al			

Signature

Examiner Name	Date
	6/15/06